

Title (en)
RESIN COMPOSITION, AND MOLDED ARTICLE PRODUCED FROM THE SAME

Title (de)
HARZZUSAMMENSETZUNG UND DARAUS HERGESTELLTER FORMKÖRPER

Title (fr)
COMPOSITION DE RÉSINE ET ARTICLE MOULÉ OBTENU À PARTIR DE CETTE COMPOSITION

Publication
EP 2113532 A4 20120215 (EN)

Application
EP 08710406 A 20080219

Priority
• JP 2008000252 W 20080219
• JP 2007043984 A 20070223
• JP 2007137924 A 20070524

Abstract (en)
[origin: EP2113532A1] Disclosed is a resin composition including a polylactic acid resin (A), a polycarbonate resin (B) and a methyl methacrylate copolymer (C). The mass ratio (A/B) between the resins (A) and (B) is 40/60 to 80/20. The ratio (MFR A /MFR B) between the melt flow rate (MFR A) of the resin (A) and the melt flow rate (MFR B) of the resin (B) is less than 10 at 240°C under a load of 21.2 N. The copolymer (C) is a copolymer between methyl methacrylate and a (meth)acrylic acid ester, and the weight average molecular weight (Mw) of the copolymer (C) is 500,000 or more. The content of the copolymer (C) is 0.1 to 20 parts by mass in relation to 100 parts by mass of the total of the resins (A) and (B).

IPC 8 full level
C08L 67/04 (2006.01); **C08K 5/1515** (2006.01); **C08K 5/29** (2006.01); **C08K 5/353** (2006.01); **C08L 33/14** (2006.01); **C08L 69/00** (2006.01)

CPC (source: EP US)
C08L 67/04 (2013.01 - EP US); **C08L 69/00** (2013.01 - EP US); **C08K 5/1515** (2013.01 - EP US); **C08K 5/29** (2013.01 - EP US); **C08K 5/353** (2013.01 - EP US); **C08L 23/0884** (2013.01 - EP US); **Y10T 428/254** (2015.01 - EP US)

Citation (search report)
• [I] WO 2006030951 A1 20060323 - TORAY INDUSTRIES [JP], et al & EP 1792941 A1 20070606 - TORAY INDUSTRIES [JP]
• [E] US 2008071038 A1 20080320 - IDO SACHIO [JP]

Cited by
EP2199341A3; EP2199342A3; US8835558B2; WO2014184057A1; US8133943B2; EP2454321B1

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